INSULCAST EPOXIES

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	Description	Color	Mix Ratio by Weight (with Curing Agent)	Viscosity (Mixed, cP)	Cure Cycle	Shore Hardness	Thermal Conductivity, (W/m °K)	Glass Transition Point, (°C)	Dielectric Constant, (KHz)	Dielectric Strength, (Volts/Mil)	Volume Resistivity, (Ohm-cm)	Coefficient of Thermal Expansion (°C)	Service Temperature, (°C)	UL Flammability Rating
insulcast 42	Unique low viscosity co-polymer that withstands severe thermal shock, exhibits low moisture absorption & excellent dielectric insulation.	Black	100:10	15,000	24hr @ 25°C	75A	0.604	-60	4.00	440	1x10¹⁵	45x10 ⁻⁶	-40 to +105	94V-0
Insulcast 101	Has excellent chemical resistance to a broad range of acids, bases and organic solvents.	Black	1:1	10,000	48hr @ 25°C	80D	0.468	80	4.40	410	1x10¹⁴	30x10-⁵	-55 to +105	None
Insulcast 116 FR	Easy-to-use, general purpose potting and casting compound. The convenient 1:1 mix ratio makes it ideal for production line mixing as well as for automatic dispensing.	Black	1:1	8,100	24hr @ 25°C	75D	0.432	80	4.40	420	1x10 ¹⁴	30x10-8	-40 to +105	94V-0
Insulcast 116 FR FC	Easy-to-use, general purpose, fast set potting and casting compound.	B l ack	1:1	9,800	16hr @ 25°C	75D	0.432	80	4.40	420	1x10 ¹⁴	30x10 ⁻⁸	-40 to +105	94V-0
Insulcast 125	Low viscosity, general purpose, good machinability.	Black	100:6-7 (Icure 9)	3,000	36hr @ 25°C	80D	0.648	80	4.2	415	5x10 ¹⁵	48x10-8	-40 to +105	None
Insulcast 136	Easy to use, excellent adhesion to metals, ceramics and most plastics.	Black	100: 6-7 (I cure 9)	30,000	36hr @ 25°C	87D	0.72	80	4.80	440	5x10 ¹⁶	40x10-8	-40 to +105	None
Insulcast 140 FR	Very high thermal conductivity.	Black	100: 3-4 (Icure 11B)	50,000	3hr @ 100°C	90-95D	2.88	100	6.30	420	1x10 ¹⁵	26x10-8	-40 to +105	94V-0
Insulcast 333	Good thermal conductivity, superior impact resistance with good adhesion to most substrates.	Black / Neutral	100:6 (I cure 9)	2,000	36hr @ 25°C	85D	0.618	80	4.4	410	1x10 ¹⁵	48x10-⁵	-40 to +105	94V - 0
Insulcast 502	Unfilled, excellent electrical & physical properties.	Clear	100:13 (Icure 9)	200	36hr @ 25°C	85D	0,23	85	4.0	425	2x10 ¹⁵	75x10 ⁻⁸	-40 to +105	None
Insulcast 504	Unfilled, excellent electrical & physical properties.	Black	100:12 (Icure 9)	200	36hr @ 25°C	75D	0.23	75	4.0	525	2.6x10 ¹⁴	61x10-8	-40 to +105	None
Insulcast LN 1-05	Non-cracking compound that is suitable for large potting applications.	B l ack	100:14	5,000	36hr @ 25°C	85D	0.648	75	5.15	400	6x10 ¹⁵	32x10 ⁻⁸	-40 to +105	None
Insulcast 961 FR	Low density syntactic foam.	Black	100:11-12 (Icure 9)	7,000	36hr @ 25°C	70D	0.172	80	2.70	375	1x10 ¹³	40x10-8	-40 to +105	None
Insulcast 985 FR	Two-part, heat cure. Semi-flexible flame retardent compund, superior shock resistance,	B l ack	1:1	50,000	16hr @ 85°C	70D	0.504	80	3.80	425	6x10 ¹⁵	32x10 ⁻⁸	-55 to +155	94V - 0
Insulcast 987 CM	Semi-flexible potting compound that exhibits excellent electrical & physical properties.	Neutral	2:3	60,000	16hr @ 85°C	65D	0.417	80	4.90	375	1x10 ¹⁴	45x10 ⁻⁶	-40 to +105	None
Insulcast 3230 LV	Low viscosity, highly filled formulation that exhibits excellent electrical properties and unusually high thermal conductivity with low thermal expansion.	B l ack	100: 5-7 (Icure 9)	6,000	36hr @ 25°C	90D	1.20	80	6.30	475	1.3x10 ¹⁵	28x10 ⁻⁵	-40 to +105	None
Insulgel 50 FC	Soft gel, fast cure compound. The product does not require vacuum de-gassing to assure bubble-free castings.	B l ack	100:25	500	12hr @ 25°C	50A	0.23	5	3.50	425	1x10 ¹⁴	45x10 ⁻⁶	-55 to +155	None
Insulgel 70 CC FR NS	Unique, flexible epoxy compound that exhibits superior thermal shock resistance. It provides reduced shrinkage and low CTE resulting in decreased stress and improved adhesion.	Black	100:10-11	3,000	24hr @ 25°C	50D	0.518	5	3.6	400	7x10 ¹²	90x10 ^{-₅}	-40 to +105	94V-0
Insulgel 90	Soft gel, low viscosity compound that does not normally require vacuum de-gassing to void-free castings & imbedments.	Clear	100:25	200	16hr @ 25°C	90A	0.23	5	3.50	375	1x10 ¹⁴	45x10 ⁻⁸	-55 to +155	None

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